





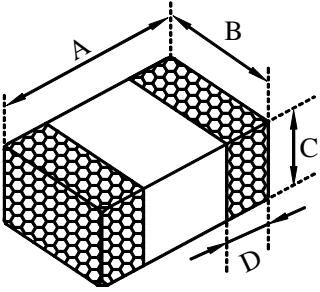
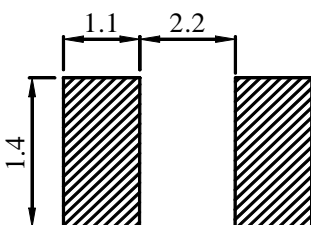
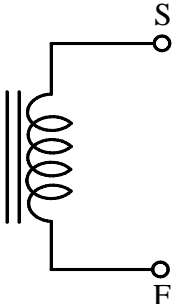
剛松股份有限公司

GANG SONG ELECTRONICS CO., LTD.

SPECIFICATION FOR APPROVAL

1.0

1/2

CUST. NAME		(Q014)			DATE	
DESCRIPTION		Multilayer Chip Beads			TYPE	
GS PART NO.		GSMA321611 - U0400			DWG. NO.	
CUST. PART NO.					GS SAMPLE NO.	
DIM	Unit in mm	MECHANICAL MEASUREMENTS				
A	3.2±0.2					  
B	1.6±0.2					
C	1.1±0.2					
D	0.4~1.0					
E						
F						
G						
H						
I						
J						
K						
L						
M						
N						
ELECTRICAL MEASUREMENTS & TEST EQUIPMENT						Remark :
NO.	Z (Ω) @100MHz /500mV	Q (min) @	SRF(min) MHz	DCR(max) (Ω)	IDC(max) (mA)	
EQU.	HP4291A			HP4338A	WK3260B WK3265B	
SPE.	400±25%			0.09	2000	
1					↓	
2						
3						
4						
5						
6						
7						
8						
9						
10						
DRAWN BY: Mavis		CHECKED BY: Ching Chung			APPROVED BY: William	

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SPECIFICATION FOR APPROVAL

1.0

2/2

CUST. NAME	(Q014)	DATE	
DESCRIPTION	Multilayer Chip Beads	TYPE	
GS PART NO.	GSMA321611 - U0400	DWG. NO.	
CUST. PART NO.		GS SAMPLE NO.	

